

Graphene Oxide-Enhanced Mixed-Structure Quasi-2D Perovskites for Stable Low-Threshold Amplified Spontaneous Emission

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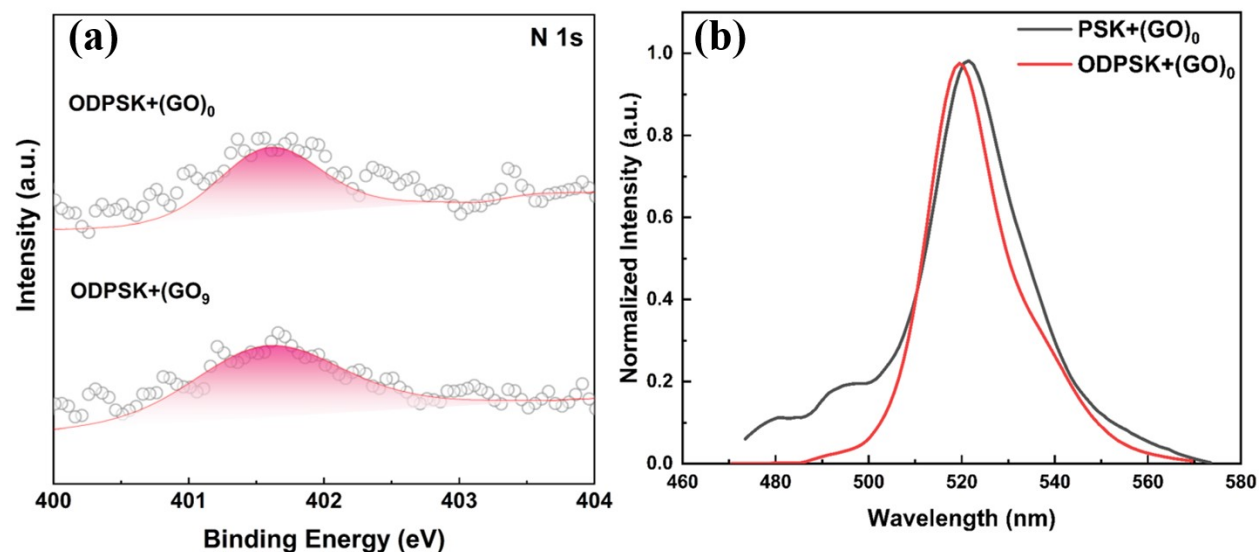


Figure S1. a) XPS spectra of N 1s in ODPSK+(GO)₀, and ODPSK+(GO)₉. b) PL spectra of PSK+(GO)₀ and ODPSK+(GO)₀ showing a blue shift.

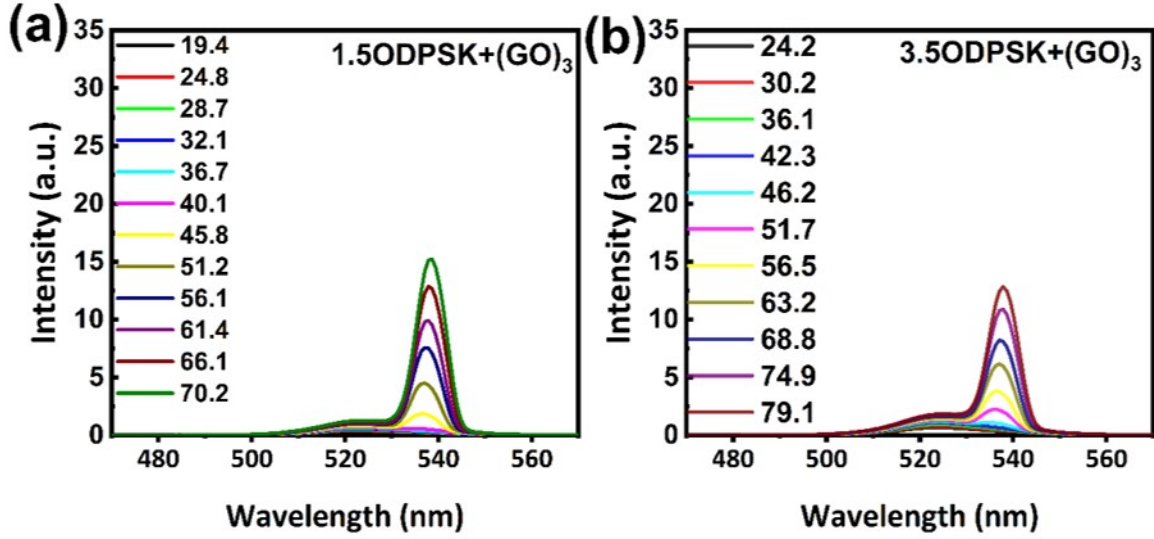


Figure S2. ASE characterizations of the perovskite films. a-b) Excitation fluence-dependent PL spectra of 1.5ODPSK+(GO)₃, and 3.5ODPSK+(GO)₃ quasi-2D perovskite films.

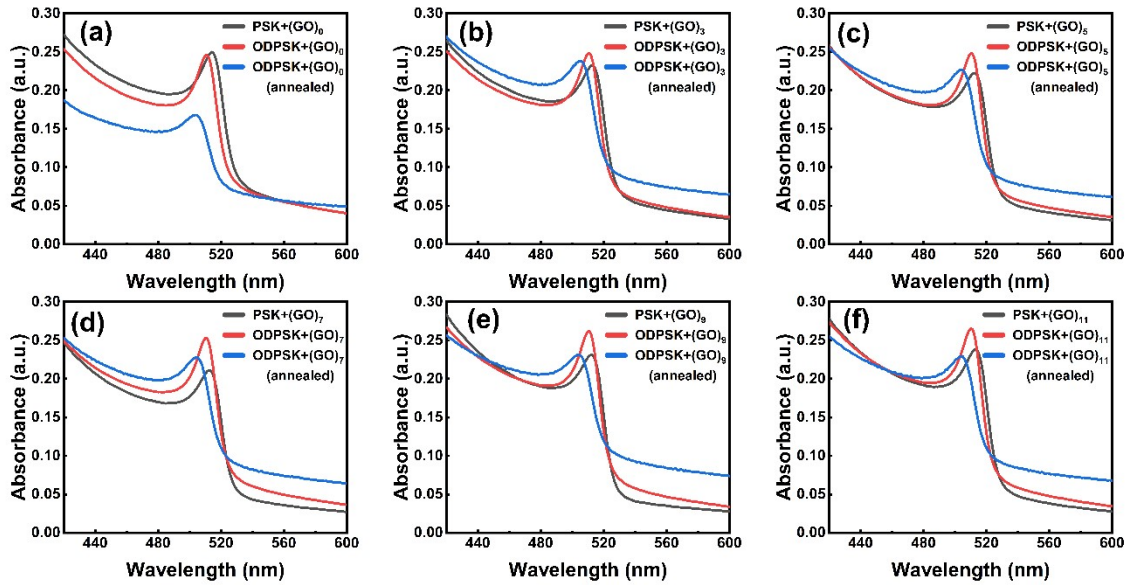


Figure S3. a-f) Absorption spectra of the pure PSK+(GO)₀, ODPSK+(GO)₀ (without annealing and annealed at 130 °C for 24 hours), and GO-treated perovskite films PSK+(GO)_x, ODPSK+(GO)_x films (without annealing and annealed at 130 °C for 24 hours).

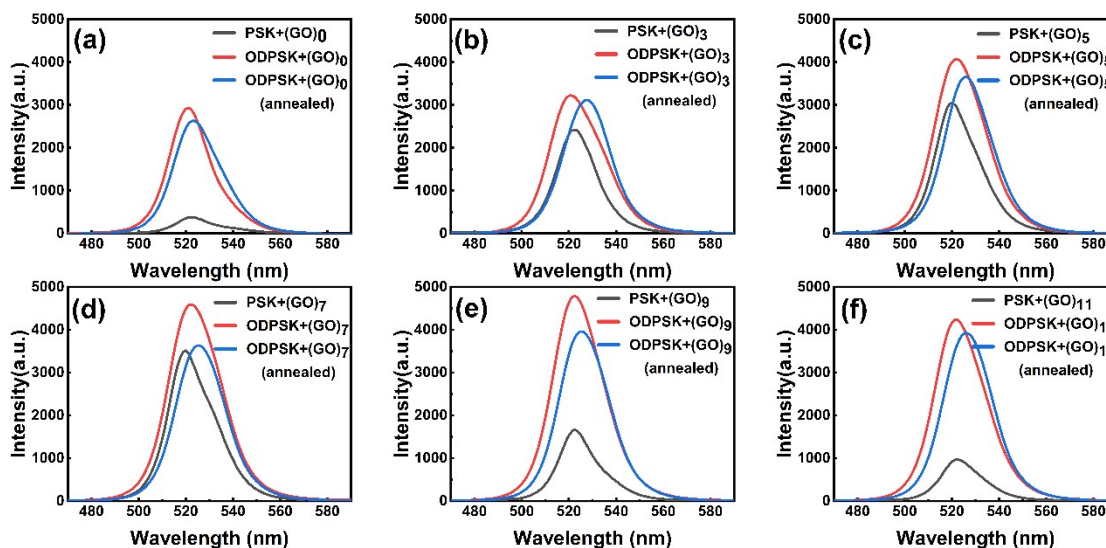


Figure S4. a-f) PL spectra of the pure PSK+(GO)₀, ODPSK+(GO)₀ (without annealing and annealed at 130 °C for 24 hours), and GO-treated perovskite films PSK+(GO)_x, ODPSK+(GO)_x films (without annealing and annealed at 130 °C for 24 hours).

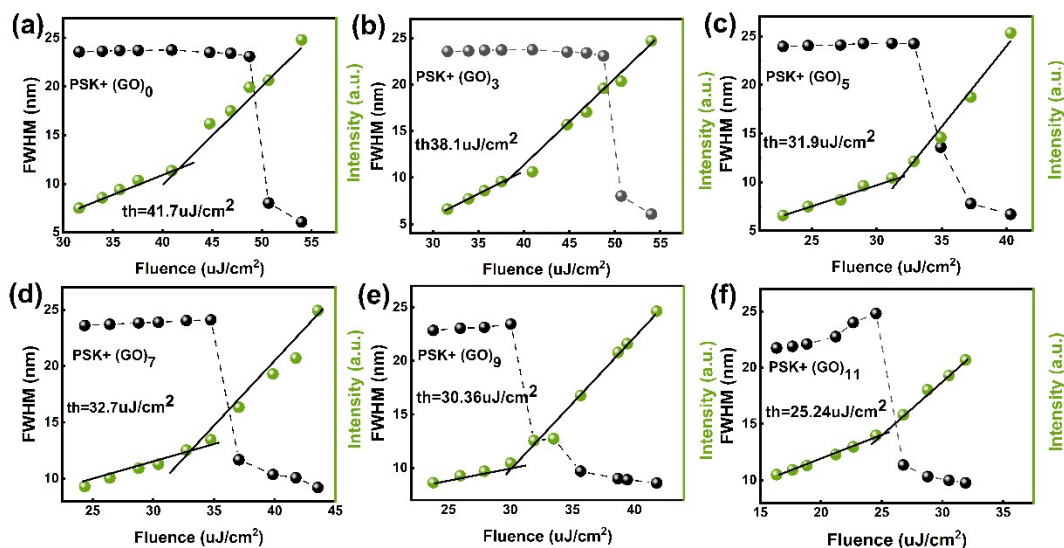


Figure S5. a-f) The FWHM and ASE intensity versus excitation fluence of the PSK+(GO)₀, PSK+(GO)₃, PSK+(GO)₅, PSK+(GO)₇, PSK+(GO)₉, and PSK+(GO)₁₁ thin films after annealing at 130 °C for 24 hours under a nitrogen atmosphere. (Fitted with the formula ($y = ax + b$)).

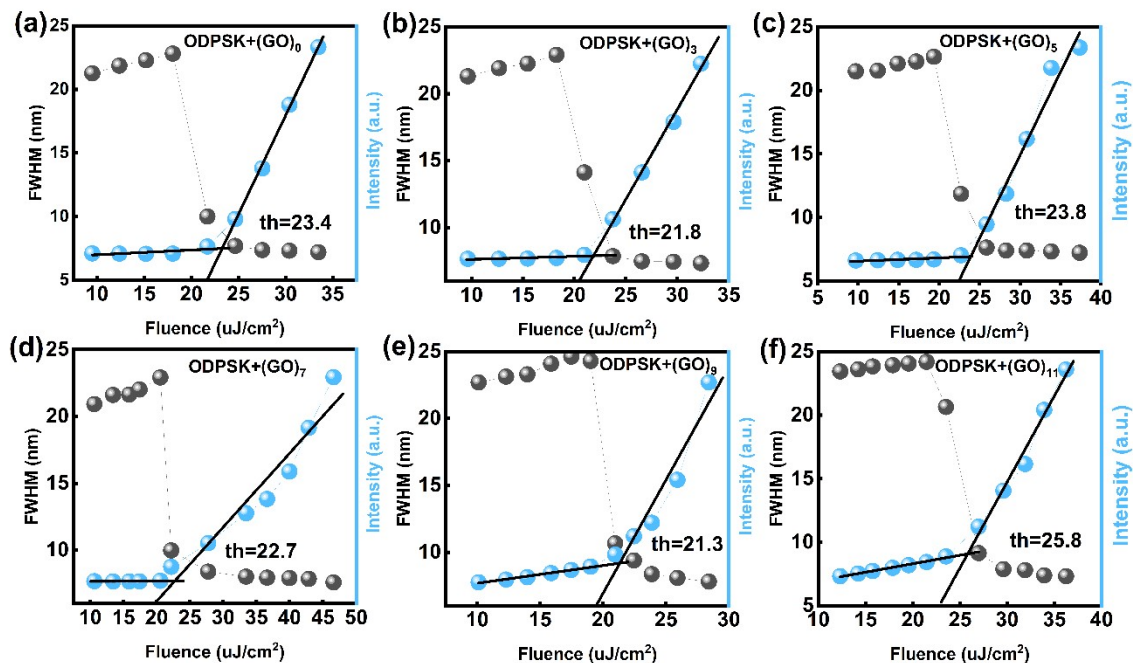


Figure S6. a-f) The FWHM and ASE intensity versus excitation fluence of the ODPSK+(GO)₀, ODPSK+(GO)₃, ODPSK+(GO)₅, ODPSK+(GO)₇, ODPSK+(GO)₉, and ODPSK+(GO)₁₁ thin films after annealing at 130 °C for 24 hours under nitrogen atmosphere. (Fitted with the formula ($y = ax + b$)).

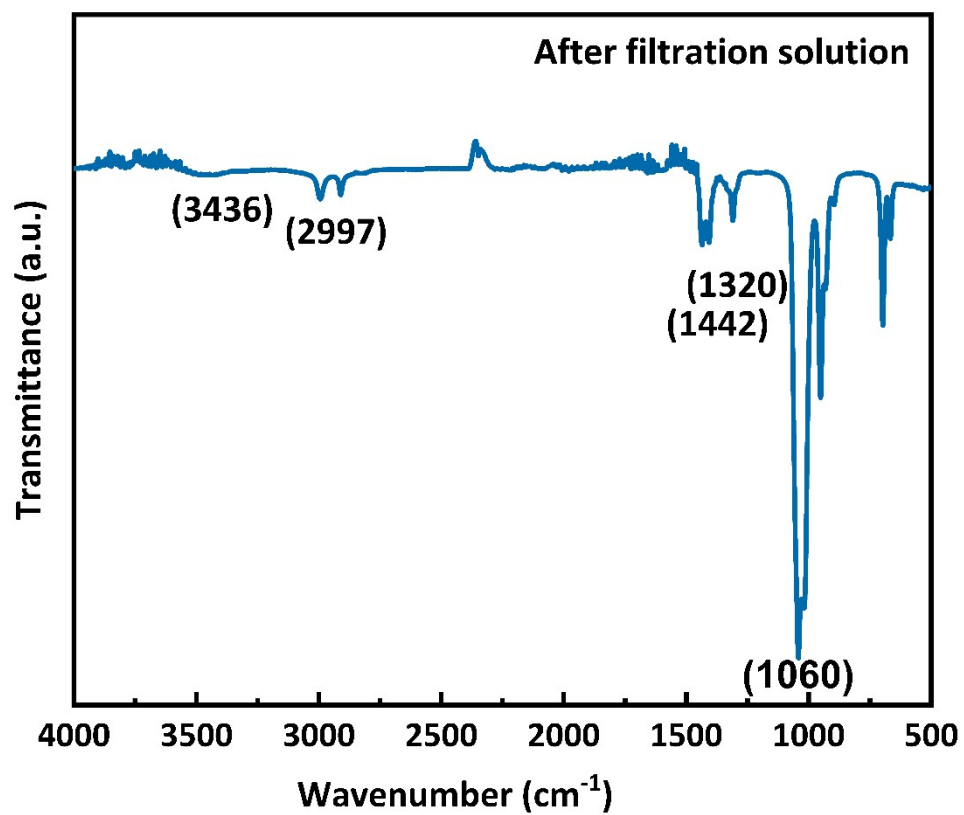


Figure S7. FTIR spectra of ODPSK+(GO)₁₁ solution after filtration.

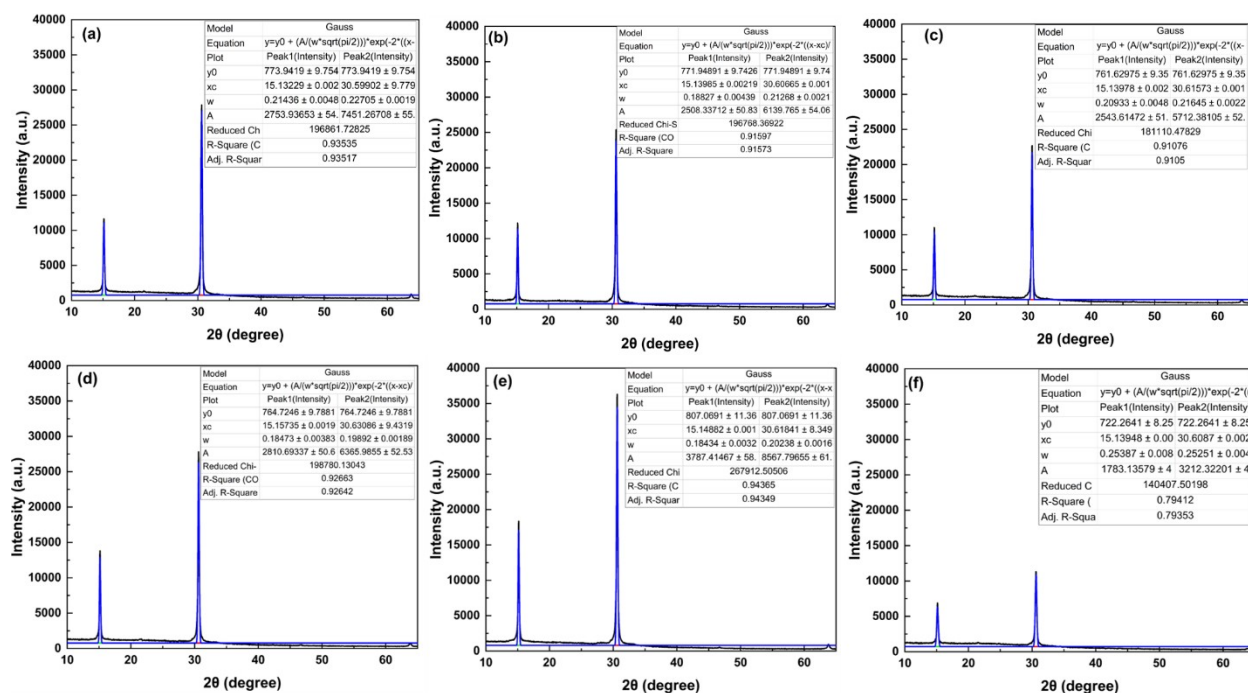


Figure S8. XRD patterns of ODPSK+(GO)₀, ODPSK+(GO)₃, ODPSK+(GO)₅, ODPSK+(GO)₇, ODPSK+(GO)₉, and ODPSK+(GO)₁₁ films showing the FWHM variations along with the fitting formula without annealing.

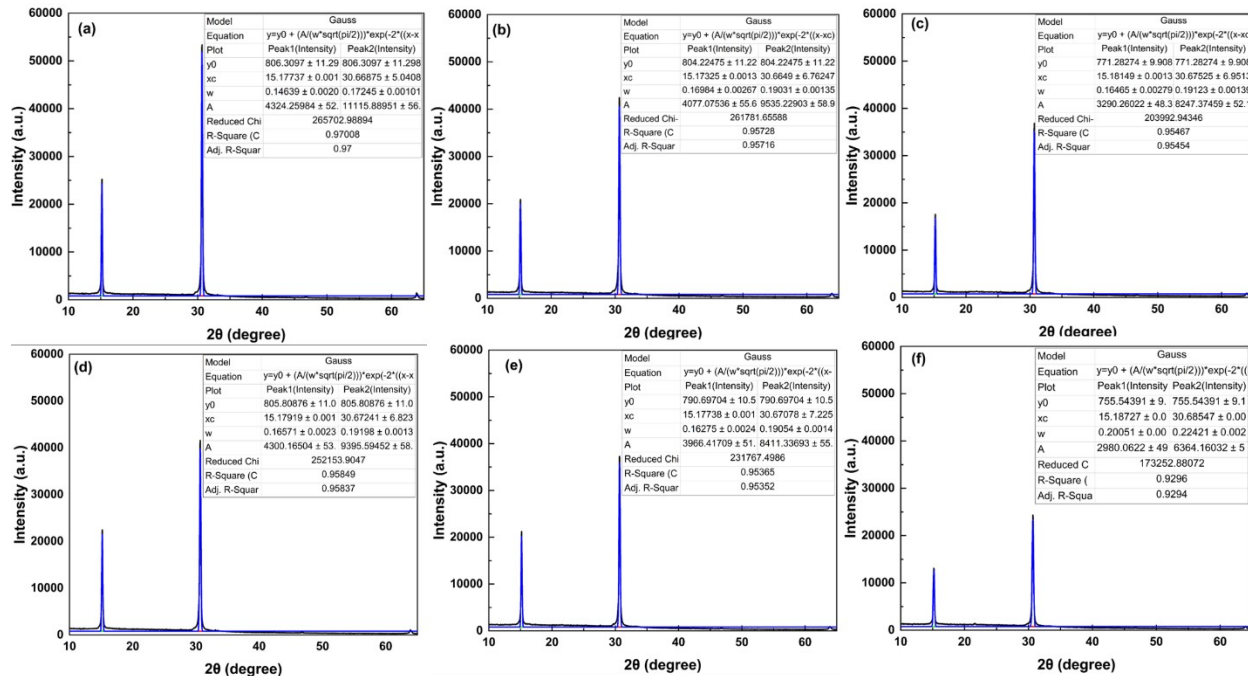


Figure S9. XRD patterns of ODPSK+(GO)₀, ODPSK+(GO)₃, ODPSK+(GO)₅, ODPSK+(GO)₇, ODPSK+(GO)₉, and ODPSK+(GO)₁₁ films showing the FWHM variations along with the fitting formula after annealing at 130 °C for 24 hours under nitrogen atmosphere.

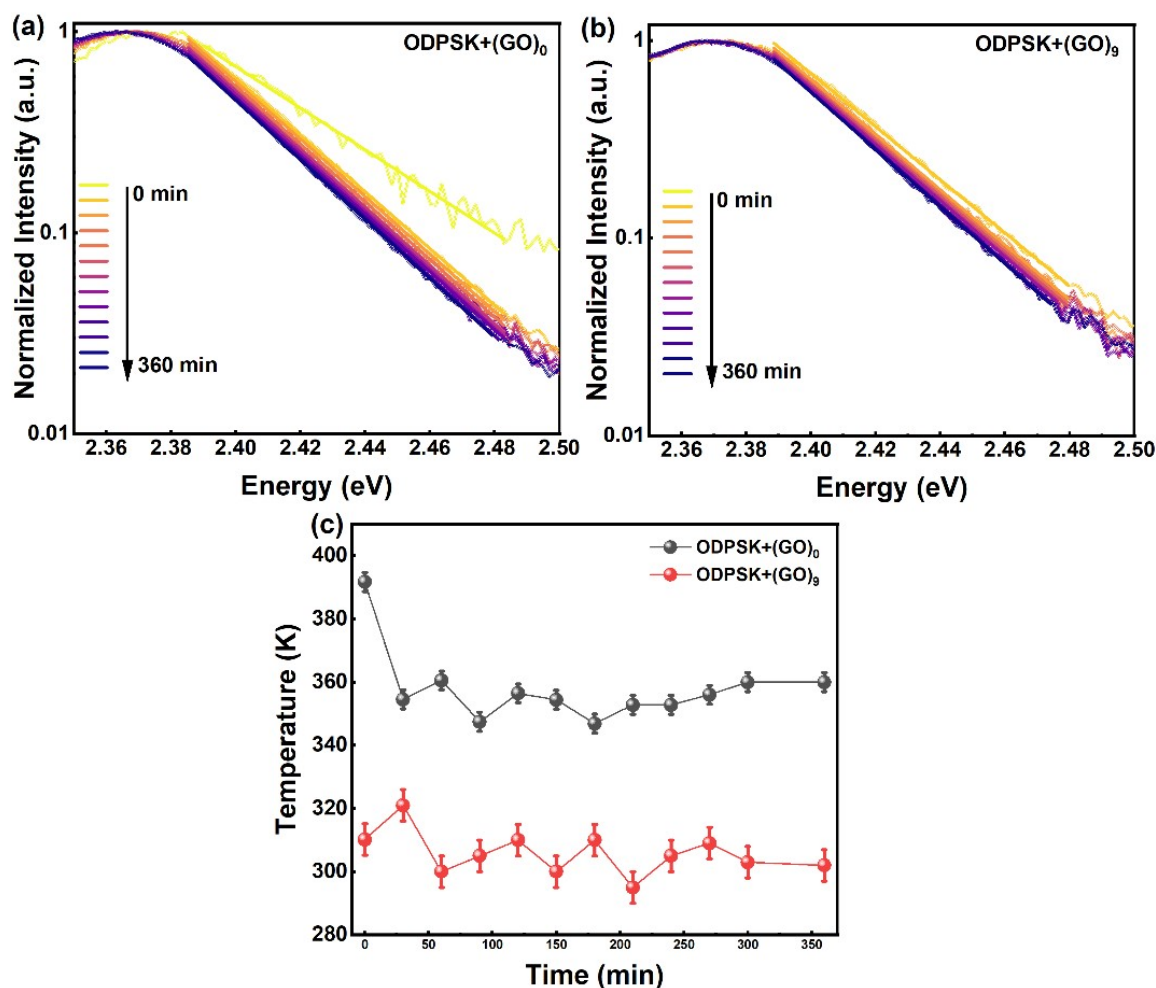


Figure S10. a-b) The normalized PL spectra of the ODPSK+(GO)₀ and ODPSK+(GO)₉ films during the CW irradiation, and c) The plasma temperature varies with irradiation time of 6 hours. These temperatures are determined by fitting the high-energy tail of photoluminescence spectra to an exponential function, $I = Ae^{-E/k_bT}$, which reflects a Boltzmann thermal distribution, where E , I energy of the photon, and the intensity of the PL spectra, k_b is the Boltzmann constant, and T represents the plasma temperature.

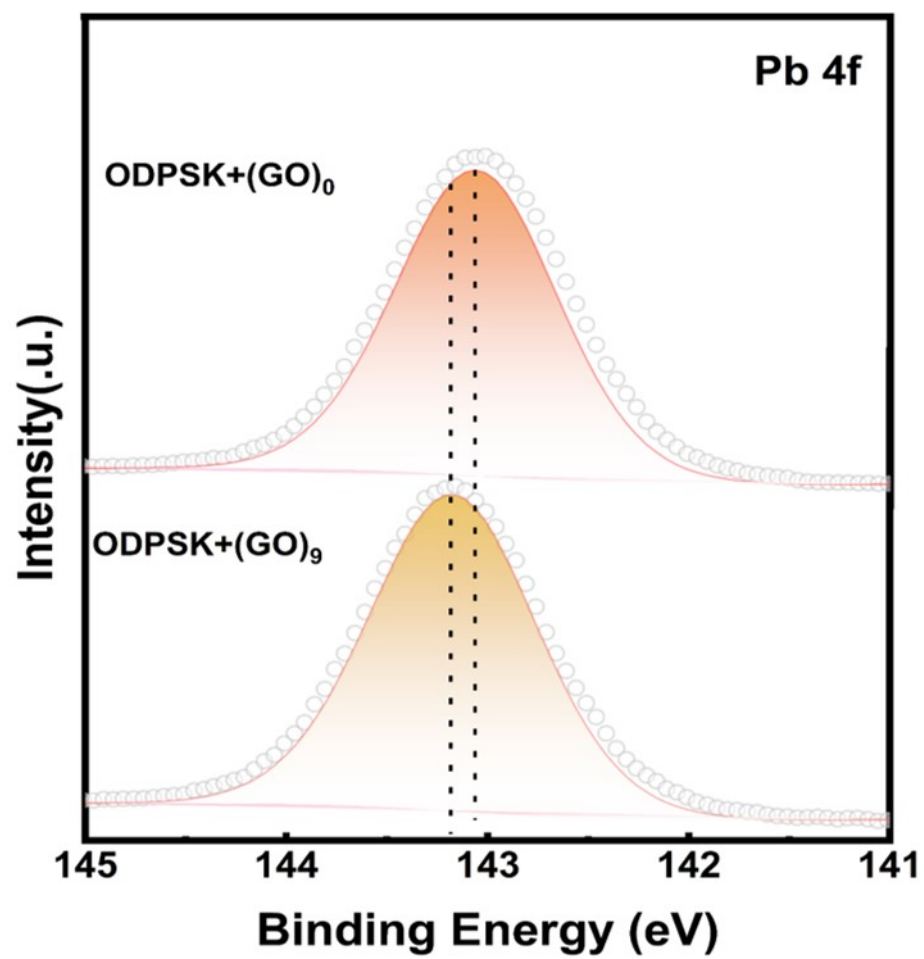


Figure S11. XPS spectra of Pb 4f in ODPSK+(GO)₀, and ODPSK+(GO)₉.

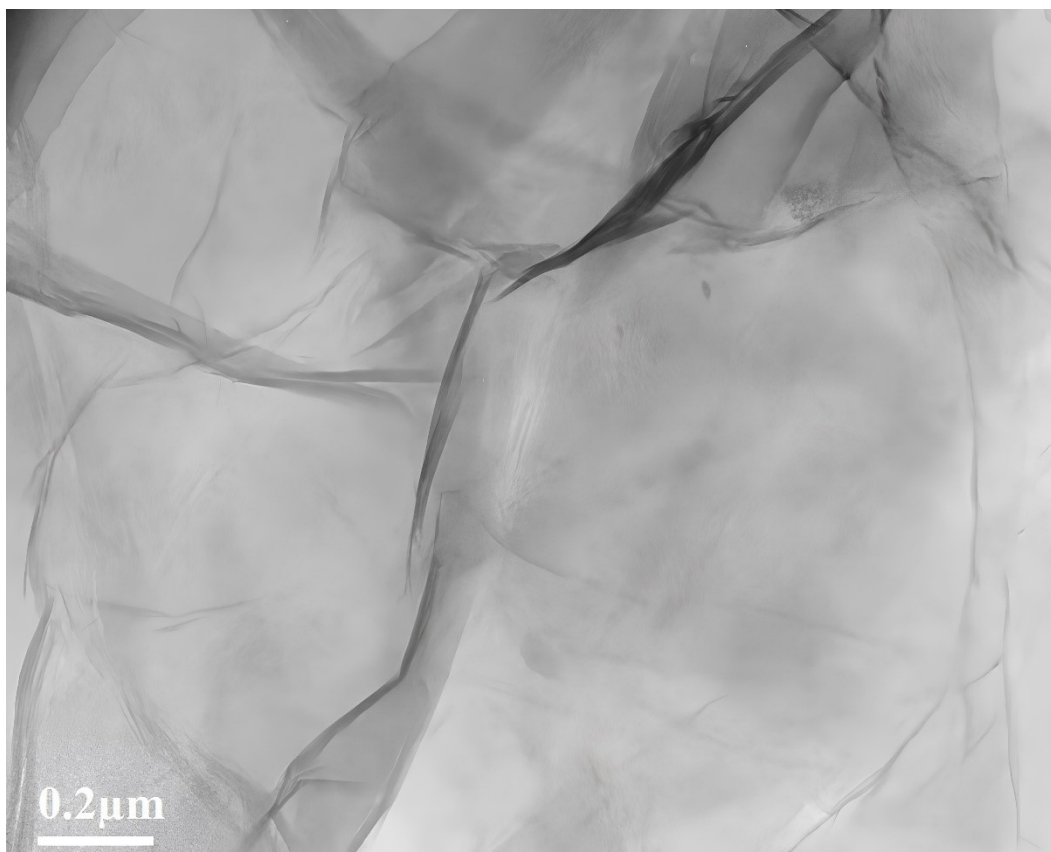


Figure S12. HR-TEM image shows sheet-like morphology of GO.

Table S1. Comparison of FWHM and threshold values of different types of films after annealing at 130 °C for 24 hours.

Film Type	FWHM after Annealing PSK+(GO) _x	FWHM after Annealing ODPSK+(GO) _x	Threshold values after Annealing PSK+(GO) _x	Threshold values after Annealing ODPSK+(GO) _x
CsPbBr ₃	11 nm	7.2 nm	41.7	21.3
CsPbBr ₃ +0.3 wt% (GO)	9.3 nm	7.3 nm	38.1	21.1
CsPbBr ₃ +0.5 wt% (GO)	8.7 nm	7.2 nm	31.9	23.1
CsPbBr ₃ +0.7 wt% (GO)	8.1 nm	7.6 nm	32.1	22.5
CsPbBr ₃ +0.9 wt% (GO)	8.1 nm	7.8 nm	30.4	20.7
CsPbBr ₃ +1.1 wt% (GO)	7.2 nm	7.3 nm	25.2	25.4

Table S2. The average longitudinal crystal sizes of the ODPSK+(GO)₀ film and the ODPSK+(GO)_x films before and after annealing at 130 °C for 24 hours.

Film Type	Before Annealing	Annealed at 130 °C after 24 hours
ODPSK+(GO) ₀	35.3 nm	47.9 nm
ODPSK+(GO) ₃	39.1 nm	42.2 nm
ODPSK+(GO) ₅	36.5 nm	43.1 nm
ODPSK+(GO) ₇	40.6 nm	42.3 nm
ODPSK+(GO) ₉	41.7 nm	43.8 nm
ODPSK+(GO) ₁₁	32.1 nm	36.9 nm

Table S3. Comparison of reported thermal stability results of ASE films

Study	Condition	RH (%)	Atmosphere	Phase+ PL shift+ Degradation)	Ref.
ODPSK+(GO) ₀	130	50	Air	Stable Phase + No shift + Significant degradation (95%) observed	This work
ODPSK+(GO) ₇	130	50	Air	Stable Phase + No shift + Significant improvement in stability with (27%) degradation.	This work
CPB-CN film	60	60	Air	split peaks observed with structure transformation + shift toward yellow+ (97%) degradation	(Huang et al., 2017)
MAPbBr ₃	60-180	NA	PMMA CB solution coating protection	The intensity of the diffraction peaks slightly increases between (60-90 °C), then decreases at 180 °C, indicating the decomposition + No Shift +NA	(Cao et al., 2023)
MAPbI ₃	150	NA		Stable Phase + No shift + %50 degradation of PCE	(You et al., 2020)

References

- 1 Cao, X., Xing, S., Lai, R., Lian, Y., Wang, Y., Xu, J., Zou, C., Zhao, B., & Di, D. *Adv. Funct. Mater.*, 2023, **33**, 1616-3028.
- 2 Huang, S., Li, Z., Wang, B., Zhu, N., Zhang, C., Kong, L., Zhang, Q., Shan, A., & Li, L, *ACS Appl. Mater. Interfaces* 2017, **9**, 7249–7258
- 3 You, P., Li, G., Tang, G., Cao, J., & Yan, F. *Energy Environ. Sci.*, 2020,**13**, 1187-1196

